

Silicon Carbide (SiC) MOSFET - 70 mohm, 1200 V, M3S, TO-247-3L

Product Preview

NTHL070N120M3S

Features

- Typ. $R_{DS(on)} = 70 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Low Switching Losses
- 100% Avalanche Tested
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

Typical Applications

- Solar Inverters
- Electric Vehicle Charging Stations
- UPS (Uninterruptible Power Supplies)
- Energy Storage Systems
- SMPS (Switch Mode Power Supplies)

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

| Parameter | | | Symbol | Value | Unit |
|--|---------------------------------------|------------------------|-----------------------------------|----------------|------|
| Drain-to-Source Voltage | | | V_{DSS} | 1200 | V |
| Gate-to-Source Voltage | | | V_{GS} | -10/+22 | V |
| Recommended Operation Values of Gate-to-Source Voltage | | T _C < 175°C | V_{GSop} | -3/+18 | > |
| Continuous Drain Current (Note 1) | Steady T _C = 25°C State | | I _D | 37 | Α |
| Power Dissipation (Note 1) | | | P _D | 252 | W |
| Continuous Drain Current (Note 1) | Steady State | T _C = 100°C | I _D | 27 | Α |
| Power Dissipation (Note 1) | | | P _D | 126 | W |
| Pulsed Drain Current (Note 2) | T _C = 25°C | | I _{DM} | 172 | Α |
| Operating Junction and Storage Temperature Range | | | T _J , T _{stg} | -55 to +175 | °C |
| Source Current (Body Diode) T _C = 25°C, V _{GS} = -3 V | | | I _S | TBD | Α |
| Single Pulse Drain-to-Source Avalanche Energy | | | E _{AS} | TBD | mJ |
| Maximum Lead Temperature for Soldering (1/8" from case for 5 s) | | | TL | 260 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

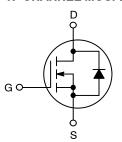
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.

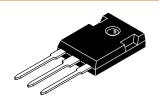
This document contains information on a product under development. **onsemi** reserves the right to change or discontinue this product without notice.

1

| V _{(BR)DSS} | R _{DS(ON)} MAX | I _D MAX | |
|----------------------|-------------------------|--------------------|--|
| 1200 V | 91 mΩ @ 18 V | 37 A | |

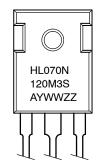
N-CHANNEL MOSFET





TO-247-3LD CASE 340CX

MARKING DIAGRAM



HL070N120M3S = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|----------|--------------------|
| NTHL070N120M3S | TO247-3L | 30 Units / Tube |

Table 1. THERMAL CHARACTERISTICS

| Parameter | | Тур | Max | Unit |
|---|-----------------|------|-----|------|
| Junction-to-Case - Steady State (Note 1) | | 0.59 | TBD | °C/W |
| Junction-to-Ambient - Steady State (Note 1) | $R_{\theta JA}$ | | 40 | |

Table 2. ELECTRICAL CHARACTERISTICS (T. J = 25°C unless otherwise specified)

| Parameter | Symbol | Test Condition | | Min | Тур | Max | Unit |
|--|--------------------------------------|--|------------------------|------|------|-----|------|
| OFF-STATE CHARACTERISTICS | | • | | • | | | |
| Drain-to-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} = 0 V, I _D = 1 mA | | 1200 | _ | _ | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | V _{(BR)DSS} /T _J | I _D = 1 mA, referenced to 25°C | | - | 0.3 | - | V/°C |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{GS} = 0 V, V _{DS} = 1200 V | T _J = 25°C | - | - | 100 | μΑ |
| Gate-to-Source Leakage Current | I _{GSS} | $V_{GS} = +22/-10 \text{ V}, V_{DS}$ | s = 0 V | - | _ | ±1 | μΑ |
| ON-STATE CHARACTERISTICS (Note 2) | | - | | - | | | |
| Gate Threshold Voltage | V _{GS(TH)} | $V_{GS} = V_{DS}$, $I_D = 7 \text{ mA}$ | | 2.04 | 2.8 | 4.4 | V |
| Recommended Gate Voltage | V_{GOP} | | | -3 | _ | +18 | V |
| Drain-to-Source On Resistance | R _{DS(on)} | V _{GS} = 18 V, I _D = 22 A, T _J = 25°C | | - | 70 | 91 | mΩ |
| | | $V_{GS} = 18 \text{ V}, I_D = 22 \text{ A},$ | T _J = 175°C | - | 150 | - | |
| Forward Transconductance | 9FS | V _{DS} = 10 V, I _D = 22 A | | - | 9 | - | S |
| CHARGES, CAPACITANCES & GATE RES | ISTANCE | | | | | | |
| Input Capacitance | C _{ISS} | V _{GS} = 0 V, f = 1 MHz, V _{DS} = 800 V | | - | 1213 | - | pF |
| Output Capacitance | C _{OSS} | | | - | 57 | - | |
| Reverse Transfer Capacitance | C _{RSS} | | | - | 6 | - | |
| Total Gate Charge | Q _{G(TOT)} | $V_{GS} = -3/18 \text{ V}, V_{DS} = 800 \text{ V},$ $I_{D} = 22 \text{ A}$ $f = 1 \text{ MHz}$ | | - | 49 | - | nC |
| Threshold Gate Charge | Q _{G(TH)} | | | - | 7 | - | |
| Gate-to-Source Charge | Q_{GS} | | | - | 14 | - | |
| Gate-to-Drain Charge | Q_{GD} | | | - | 16 | - | |
| Gate-Resistance | R_{G} | | | - | 1.31 | - | Ω |
| SWITCHING CHARACTERISTICS | | - | | - | | | |
| Turn-On Delay Time | t _{d(ON)} | $V_{GS} = -3/18 \text{ V}, V_{DS} = 800 \text{ V},$ | | - | 10 | - | ns |
| Rise Time | t _r | I_D = 22 A, R_G = 4.5 Ω Inductive load (Note 3) |) | _ | 27 | - | |
| Turn-Off Delay Time | t _{d(OFF)} | | | _ | 20 | - | |
| Fall Time | t _f | - - - - | | _ | 12 | - | |
| Turn-On Switching Loss | E _{ON} | | | _ | 357 | - | μJ |
| Turn-Off Switching Loss | E _{OFF} | | | - | 89 | - | |
| Total Switching Loss | E _{tot} | | | - | 445 | - | |
| SOURCE-DRAIN DIODE CHARACTERIST | ics | | | | | | |
| Continuous Source-Drain Diode Forward Current | I _{SD} | $V_{GS} = -3 \text{ V}, T_{C} = 25^{\circ}\text{C}$ | ; | _ | - | 39 | Α |
| Pulsed Source-Drain Diode Forward Current (Note 2) | I _{SDM} | | | - | - | 133 | |
| Forward Diode Voltage | V_{SD} | V _{GS} = -3 V, I _{SD} = 22 A | . T. – 25°C | _ | 4.5 | _ | V |

Table 2. ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified) (continued)

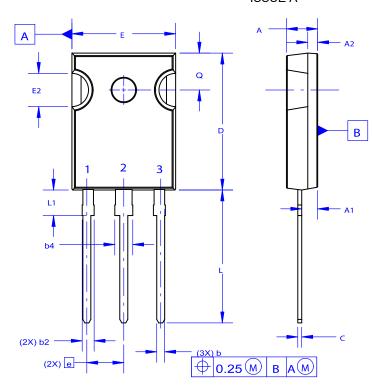
| Parameter | Symbol | Test Condition | Min | Тур | Max | Unit | |
|------------------------------------|------------------|--|-----|-----|-----|------|--|
| SOURCE-DRAIN DIODE CHARACTERISTICS | | | | | | | |
| Reverse Recovery Time | t _{RR} | $V_{GS} = -3/18 \text{ V}, I_{SD} = 22 \text{ A},$ $dI_S/dt = 1000 \text{ A}/\mu\text{s}, V_{DS} = 800 \text{ V}$ | - | 22 | - | ns | |
| Reverse Recovery Charge | Q _{RR} | dl _S /dt = 1000 A/μs, V _{DS} = 800 V | - | 102 | - | nC | |
| Reverse Recovery Energy | E _{REC} | | - | 3 | - | μJ | |
| Peak Reverse Recovery Current | I _{RRM} | | - | 8 | - | Α | |
| Charge Time | T _A | 1 | - | 13 | _ | ns | |
| Discharge Time | T _B | 1 | - | 9 | _ | ns | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. E_{ON}/E_{OFF} result is with body diode

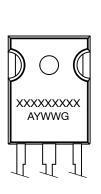
PACKAGE DIMENSIONS

TO-247-3LD CASE 340CX **ISSUE A**





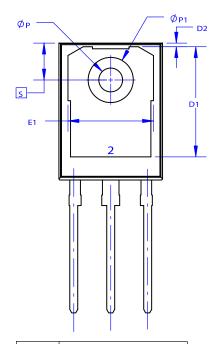
- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.





XXXXX = Specific Device Code Α = Assembly Location = Year

WW = Work Week G = Pb-Free Package



| | MILLIMETERS | | | | | |
|--------------|-------------|-------|-------|--|--|--|
| D i M | MIN | NOM | MAX | | | |
| Α | 4.58 | 4.70 | 4.82 | | | |
| A1 | 2.20 | 2.40 | 2.60 | | | |
| A2 | 1.40 | 1.50 | 1.60 | | | |
| D | 20.32 | 20.57 | 20.82 | | | |
| Е | 15.37 | 15.62 | 15.87 | | | |
| E2 | 4.96 | 5.08 | 5.20 | | | |
| е | ~ | 5.56 | ~ | | | |
| L | 19.75 | 20.00 | 20.25 | | | |
| L1 | 3.69 | 3.81 | 3.93 | | | |
| ØΡ | 3.51 | 3.58 | 3.65 | | | |
| Q | 5.34 | 5.46 | 5.58 | | | |
| S | 5.34 | 5.46 | 5.58 | | | |
| b | 1.17 | 1.26 | 1.35 | | | |
| b2 | 1.53 | 1.65 | 1.77 | | | |
| b4 | 2.42 | 2.54 | 2.66 | | | |
| С | 0.51 | 0.61 | 0.71 | | | |
| D1 | 13.08 | ~ | ~ | | | |
| D2 | 0.51 | 0.93 | 1.35 | | | |
| E1 | 12.81 | ~ | ~ | | | |
| ØP1 | 6.60 | 6.80 | 7.00 | | | |

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for SiC MOSFETs category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

NTC040N120SC1 HC3M001K170J IMBG65R048M1HXTMA1 IMW120R045M1 SCT3080ALGC11 C3M0120100K C2M1000170J
C3M0120090J C3M0065090J C3M0280090J SCT2750NYTB SCT2H12NYTB C3M0021120D C3M0016120K C3M0045065D
C3M0045065K E3M0120090J C3M0065090J-TR C3M0120100J C3M0075120J DMWS120H100SM4 DMWSH120H28SM4
DMWSH120H90SM4 DMWSH120H90SM4Q DMWSH120H28SM4Q DMWSH120H90SCT7Q DMWSH120H28SM3
DMWSH120H43SM3 DMWSH120H90SM3 DMWSH120H28SM3Q DMWSH120H90SM3Q DIF120SIC053-AQ DIW120SIC059-AQ
G2R1000MT17D G3R60MT07K G2R50MT33K G3R12MT12K G3R160MT12D G3R160MT12J-TR G3R160MT17D G3R40MT17J-TR
G3R20MT12K G3R20MT12N G3R20MT17K G3R20MT17N G3R30MT12J-TR G3R30MT12K G3R350MT12D G3R40MT12D
G3R40MT12J